

ABSTRACT OF THE DISCLOSURE

In an LED lamp, a copper film is first formed on a substrate by plating. A resist is then bonded onto the copper film so that shaped like a ring viewed from the whole of the LED lamp. A nickel and a gold film are formed on a portion of the copper film where the resist is not bonded. Next, an adhesive agent is applied onto a bottom of the lamp house so that the lamp house is bonded onto the substrate through the adhesive agent. A transparent epoxy resin is packed in the frame of the lamp house and hardened by heating to perform resin sealing. Since the resist is bonded onto the surface of copper having a large number of fine irregularities sufficient to ensure a large contact area and excellent in adhesion, separation can be prevented from being caused by thermal stress.